Panasonic INDUSTRY

Thinner

High-density wiring

Warpage control

Applications

IC Package/Mobile

High-density, advanced package for mobile devices (PoP, MCP, Mold underfill package, etc.)

LEXCM CF

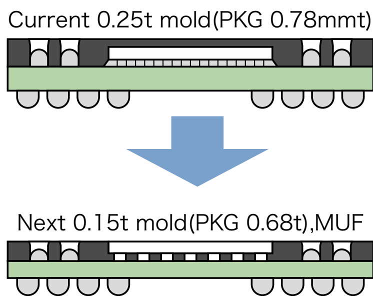
CV8710 CV8760

Thin surface mounting semiconductor encapsulation materials

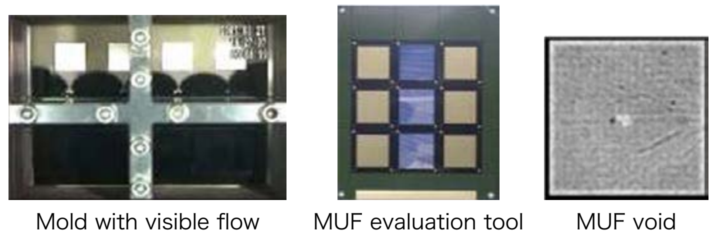
Corresponding to the high-density wiring and thinner (Fillability for narrow gap and narrow pitch)
Corresponding to the flip-chip mounting. Making the substrate thinner (Package warpage control)

Trends and required performance

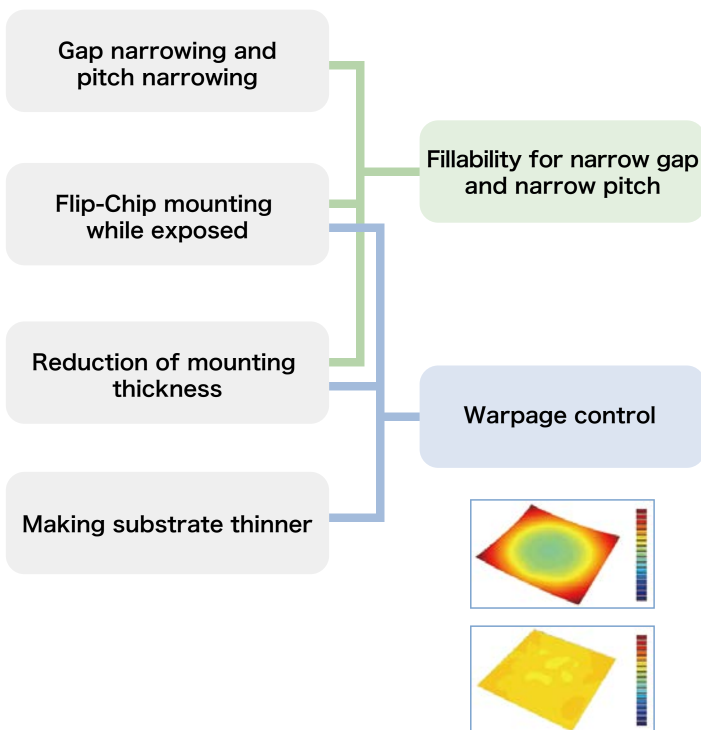
ex) MUF(Mold underfill) of PoP-b



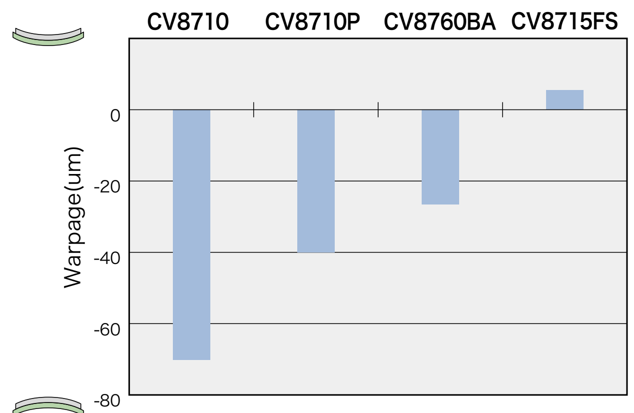
Use of high moldability-evaluation technology has achieved excellent fillability



Mold with visible flow　MUF evaluation tool　MUF void

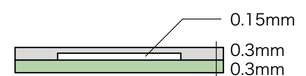


Line-up of materials selectable according to warpage



0.3t mold FBGA

PKG size : 12×12mm
Substrate : BT 0.3mmt
Die : 8×8×0.15mmt
Mold thickness : 0.3mmt



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